

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS3705-30D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70530
TPS3705-30D.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70530
TPS3705-30D.B	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70530
TPS3705-30DGN	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAT
TPS3705-30DGN.A	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAT
TPS3705-30DGN.B	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAT
TPS3705-30DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70530
TPS3705-30DR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70530
TPS3705-30DR.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70530
TPS3705-33D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	70533
TPS3705-33D.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	70533
TPS3705-33D.B	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	70533
TPS3705-33DG4	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	70533
TPS3705-33DGN	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAU
TPS3705-33DGN.A	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAU
TPS3705-33DGN.B	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAU
TPS3705-33DGNR	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAU
TPS3705-33DGNR.A	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAU
TPS3705-33DGNR.B	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAU
TPS3705-33DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	70533
TPS3705-33DR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	70533
TPS3705-33DR.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	70533
TPS3705-50D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70550
TPS3705-50D.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70550
TPS3705-50D.B	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70550
TPS3705-50DG4	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70550
TPS3705-50DGN	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAV
TPS3705-50DGN.A	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAV
TPS3705-50DGN.B	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAV

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS3705-50DGNG4	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAV
TPS3705-50DGNR	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAV
TPS3705-50DGNR.A	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAV
TPS3705-50DGNR.B	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAV
TPS3705-50DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70550
TPS3705-50DR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70550
TPS3705-50DR.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70550
TPS3705-50DRG4	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70550
TPS3707-25D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70725
TPS3707-25D.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70725
TPS3707-25DGN	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAW
TPS3707-25DGN.A	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAW
TPS3707-25DGNR	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAW
TPS3707-25DGNR.A	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAW
TPS3707-25DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70725
TPS3707-25DR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70725
TPS3707-30D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70730
TPS3707-30D.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70730
TPS3707-30DGN	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAX
TPS3707-30DGN.A	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAX
TPS3707-30DGNR	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAX
TPS3707-30DGNR.A	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAX
TPS3707-30DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70730
TPS3707-30DR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70730
TPS3707-33D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70733
TPS3707-33D.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70733
TPS3707-33DGN	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAY
TPS3707-33DGN.A	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAY
TPS3707-33DGNR	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAY
TPS3707-33DGNR.A	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAY
TPS3707-33DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70733

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS3707-33DR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70733
TPS3707-50D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70750
TPS3707-50D.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70750
TPS3707-50DGN	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAZ
TPS3707-50DGN.A	Active	Production	HVSSOP (DGN) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAZ
TPS3707-50DGNR	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAZ
TPS3707-50DGNR.A	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AAZ
TPS3707-50DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70750
TPS3707-50DR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	70750

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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